# Product Change Notification - KSRA-08NNFY461 (Printer Friendly)

**Date:**

11 Jan 2017

**Product Category:**

8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers

**Notification subject:**

CCB 2800 Initial Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

**Notification text:**

**PCN Status:**
Initial notification

**Microchip Parts Affected:**
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 200K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site.

**Pre Change:**

Using gold (Au) bond wire and C194 lead frame material

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material

**Pre and Post Change Summary:**

| | Pre Change | Post Change |
|---|---|---|
| **Assembly Site** | NSEB assembly site | NSEB assembly site |
| **Wire material** | Au wire | CuPdAu wire |
| **Die attach material** | 8600 | 8600 |
| **Molding compound material** | G700LTD | G700LTD |
| **Lead frame material** | C194 | C194 |

**Impacts to Data Sheet:**
None

**Change Impact:**
None

**Reason for Change:**
To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

**Change Implementation Status:**
In Progress

**Estimated Qualification Completion Date:**
**April 2017**

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

**Time Table Summary:**

| | December 2016 | | | | | -> | April 2017 | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|
| Workweek | 49 | 50 | 51 | 52 | 53 | | 14 | 15 | 16 | 17 | 18 |
| Initial PCN Issue Date | | | | | X | | | | | | |
| Qual Report Availability | | | | | | | | | | | X |
| Final PCN Issue Date | | | | | | | | | | | X |

**Method to Identify Change:**
Traceability code

**Qualification Plan:**
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

**Revision History:**
**December 29, 2016:** Issued initial notification.
**January 11, 2017:** Re-issued initial notification to change the lead frame material from A194 to C194 for consistency.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**
PCN_KSRA-08NNFY461_Affected CPN.pdf
PCN_KSRA-08NNFY461_Qual Plan.pdf
PCN_KSRA-08NNFY461_Affected CPN.xlsx
Please contact your local Microchip sales office with questions or concerns regarding this notification.

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